杭芯科技
HUTCHIP

HCNS3902

30V N-Channel MOSFET

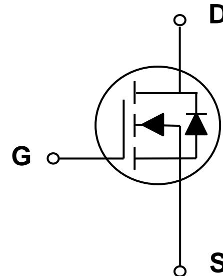
General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

Features

V_{DS}	30V
I_D (at V_{GS}=10V)	130A
$R_{DS(ON)}$ (at V_{GS}=10V)	1.5mΩ(Typ)

PDFN5x6



Absolute Maximum Ratings **T_A=25°C unless otherwise noted**

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	±20	V
Drain Current-Continuous	TC=25°C	I_D	130	A
	TC=100°C	I_D	81	A
Drain Current – Pulsed		I_{DM}	260	A
Single Pulse Avalanche Energy		EAS	256	mJ
Maximum Power Dissipation		P_D	96	W
Junction and Storage Temperature Range		T_J,T_{STG}	-55 To 150	℃

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Thermal Resistance junction-case	$R_{\theta Jc}$		0.9	℃ /W
Thermal Resistance junction-to-Ambient	$R_{\theta JA}$		62	℃ /W

Electrical Characteristics (TJ=25℃ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V I_D=250μA	30			V
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS}=30V,V_{GS}=0V			1	μA
I_{GSS}	Gate-Body Leakage Current	V_{GS}=±20V,V_{DS}=0V			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS},I_D=250μA	1.0	1.6	2.2	V
$R_{DS(ON)}$	Drain-Source On-State Resistance	V_{GS}=10V, I_D=20A		1.5	1.95	mΩ
		V_{GS}=4.5V, I_D=10A		2.4	3.35	mΩ
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	V_{DS}=15V,V_{GS}=0V, F=1.0MHz		3090		pF
C_{oss}	Output Capacitance			1620		pF
C_{rss}	Reverse Transfer Capacitance			140		pF
SWITCHING PARAMETERS						
$t_{d(on)}$	Turn-on Delay Time	V_{GS}=10V V_{DD}=15V I_D=15A R_{GEN}=3Ω		17		nS
t_r	Turn-on Rise Time			11		nS
$t_{d(off)}$	Turn-Off Delay Time			52		nS
t_f	Turn-Off Fall Time			22		nS
Q_g	Total Gate Charge	V_{DS}=15V,I_D=20A, V_{GS}=10V		47.6		nC
Q_{gs}	Gate-Source Charge			9.63		nC
Q_{gd}	Gate-Drain Charge			13.5		nC
V_{SD}	Diode Forward Voltage	V_{GS}=0V,I_{SD}=1A		0.7	1.3	V
R_g	Gate resistance	V_{GS}=0V, V_{DS}=0V, F=1MHz		2.1		Ω

Note：

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%.
3. Essentially independent of operating temperature.
4. V_{DD}=20V,I_{AR}=32A,L=0.5mH,R_G=25Ω,Starting TJ=25℃.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

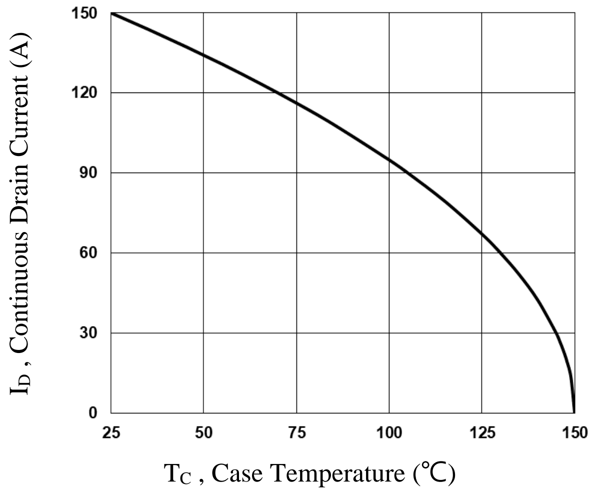


Fig.1 Continuous Drain Current vs. TC

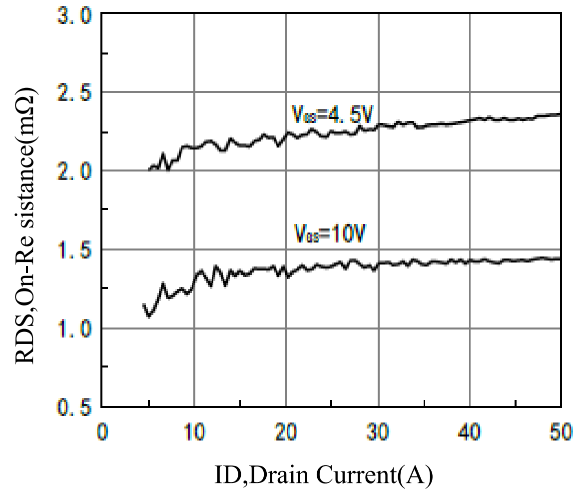


Fig.2 Normalized RDSON vs. ID

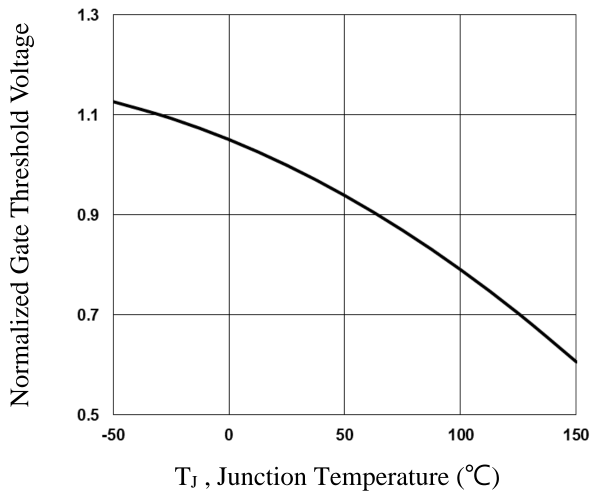


Fig.3 Normalized V_{th} vs. T_J

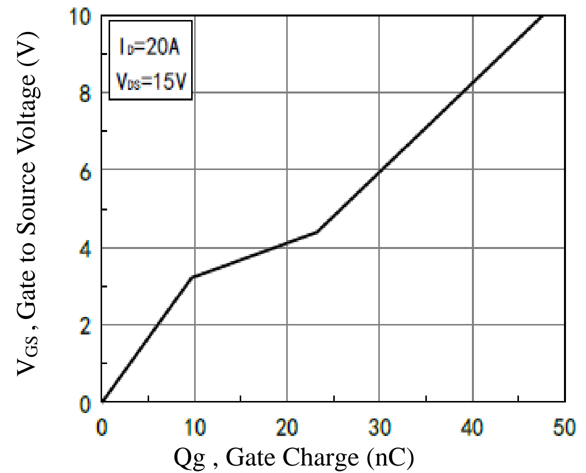


Fig.4 Gate Charge Characteristics

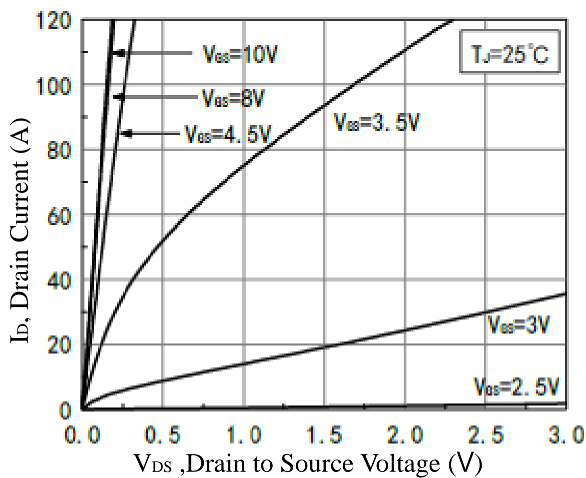


Fig.5 Typical Output Characteristics

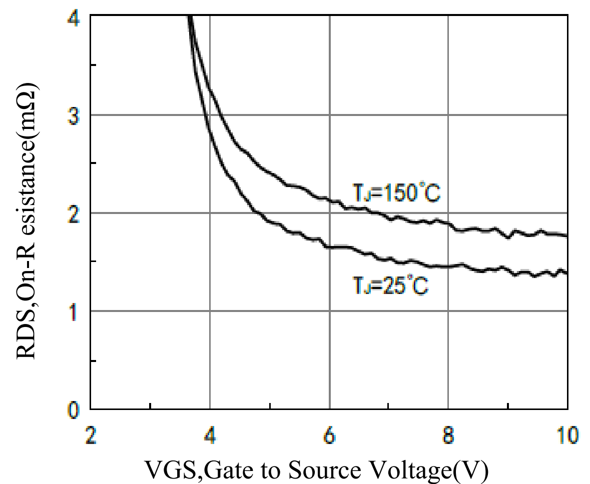


Fig.6 Turn-On Resistance vs. ID

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

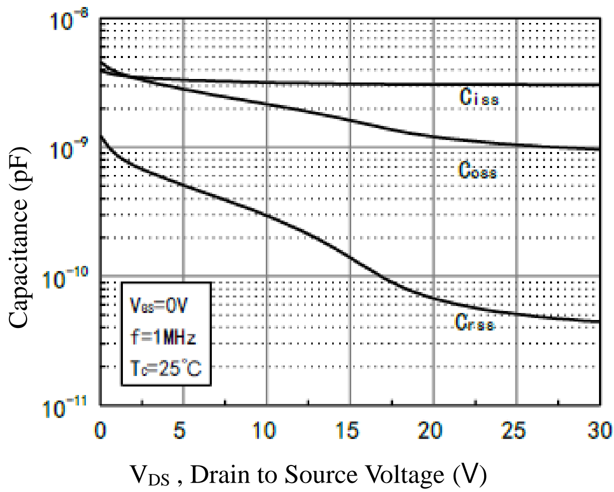


Fig.7 Capacitance Characteristics

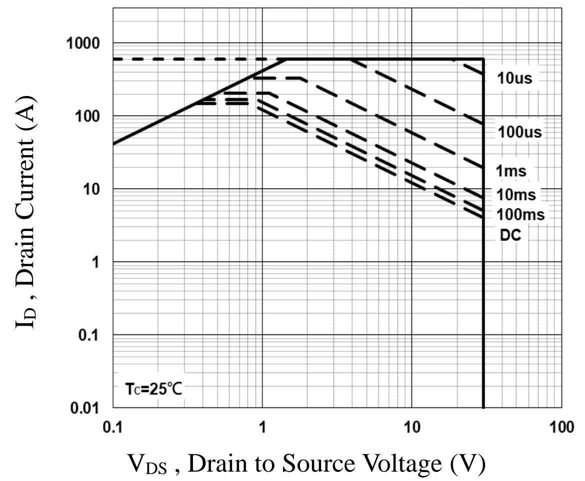


Fig.8 Maximum Safe Operation Area

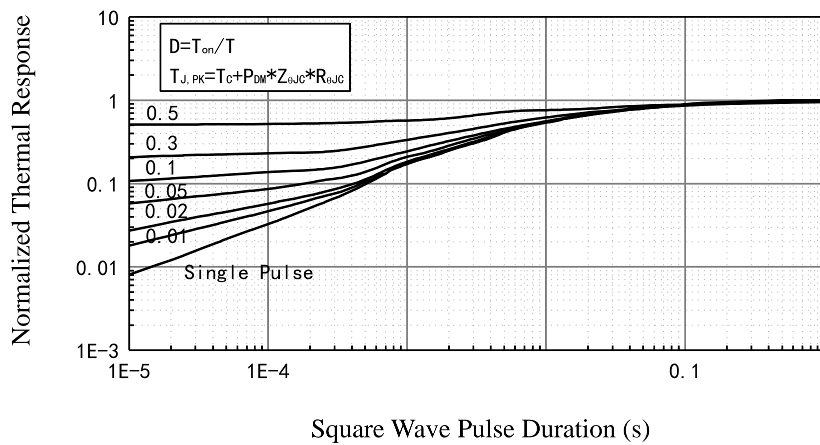


Fig.9 Normalized Transient Impedance

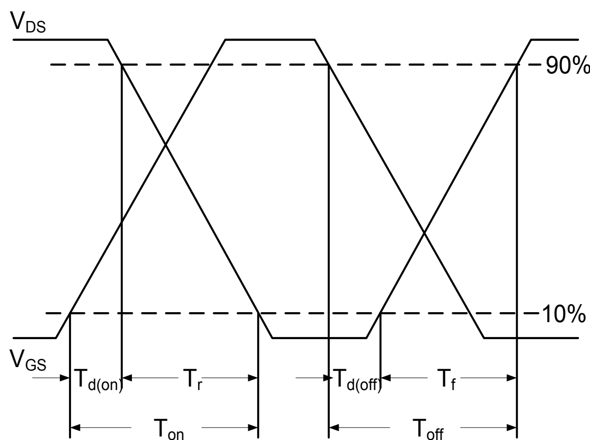


Fig.10 Switching Time Waveform

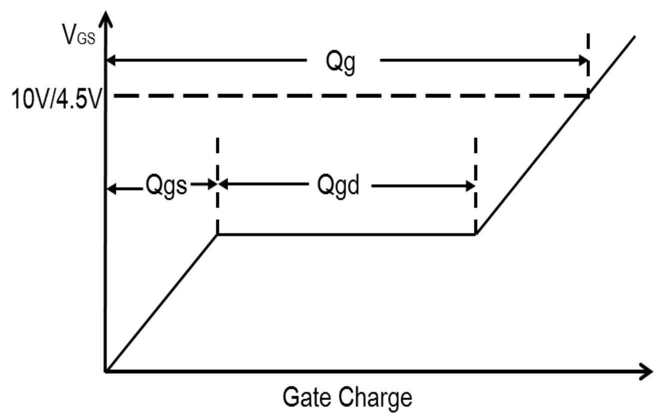
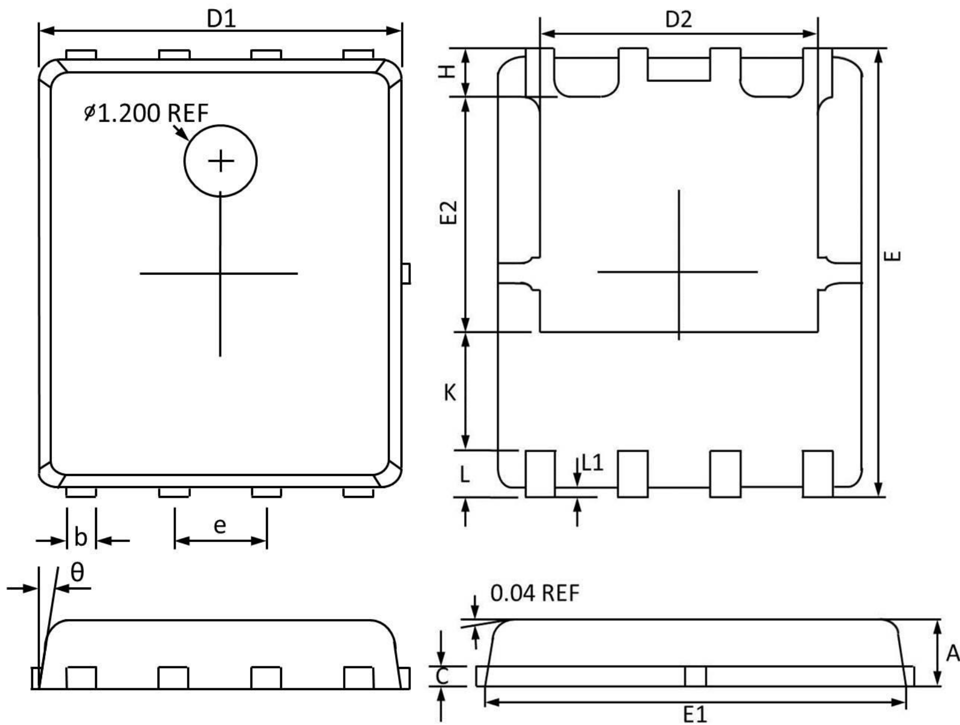


Fig.11 Gate Charge Waveform

PDFN5x6 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	1.100	0.800	0.043	0.031
b	0.510	0.330	0.020	0.013
C	0.300	0.200	0.012	0.008
D1	5.100	4.800	0.201	0.189
D2	4.100	3.610	0.161	0.142
E	6.200	5.900	0.244	0.232
E1	5.900	5.700	0.232	0.224
E2	3.780	3.350	0.149	0.132
e	1.27BSC		0.05BSC	
H	0.700	0.410	0.028	0.016
K	1.500	1.100	0.059	0.043
L	0.710	0.510	0.028	0.020
L1	0.200	0.060	0.008	0.002
θ	12°	0°	12°	0°